Claims

1. A punching assembly comprising:
a plurality of selectively replaceable die inserts upon which a punch impinges;
a die block having recesses for receiving the selectively replaceable die inserts;
wherein said inserts correspond to a punch pattern specific to a predetermined IC package arrangement.

2. The punching assembly according to claim 1, wherein said predetermined IC package includes a QFN arrangement.

3. The punching assembly according to claim 2, wherein said QFN arrangement includes a 3x3, 4x4 or 5x5 arrangement.